



## 200V N-Channel Trench Power MOSFET

### General Description

The SJA02N5000 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a wide variety of applications.

### Features

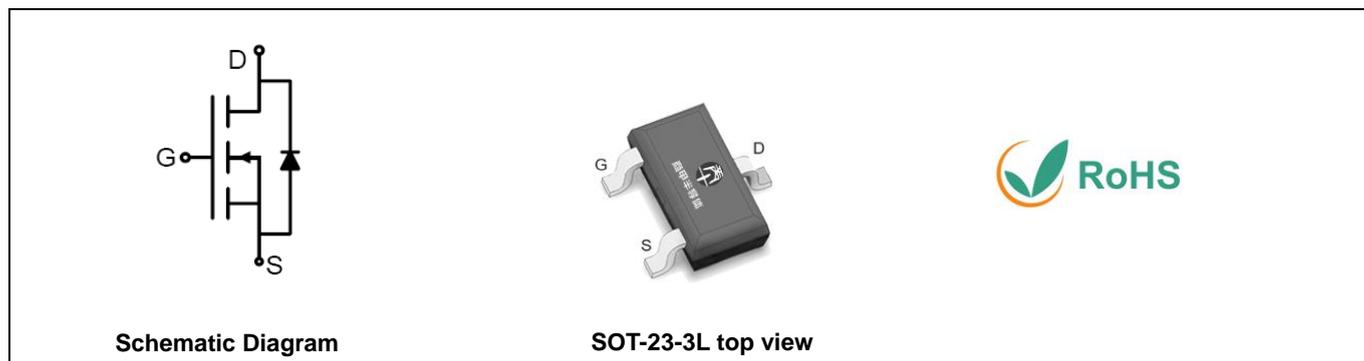
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handling capability
- Lead free product is acquired

### Application

- PWM Applications
- Load Switch
- Power Management

### Key Performance Parametes

Parameter	Value	Unit
$V_{DS}$	200	V
$R_{DS(ON\_TYP)}$	505	m $\Omega$
$I_D$	1.24	A
$Q_G$	16.8	nC



### Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Reel Size	Tape width	Quantity
SJA02N5000	2001	SOT-23-3L			

**Table 1. Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0V$ )	200	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0V$ )	$\pm 20$	V
$I_D$	Drain Current-Continuous( $T_A=25^\circ\text{C}$ )	1.24	A
	Drain Current-Continuous( $T_A=100^\circ\text{C}$ )	0.8	A
$I_{DM (pluse)}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	5.2	A
$P_D$	Maximum Power Dissipation( $T_A=25^\circ\text{C}$ )	2.4	W
	Maximum Power Dissipation( $T_A=100^\circ\text{C}$ )	1	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ\text{C}$

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		52	$^\circ\text{C/W}$



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Table 3. Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)

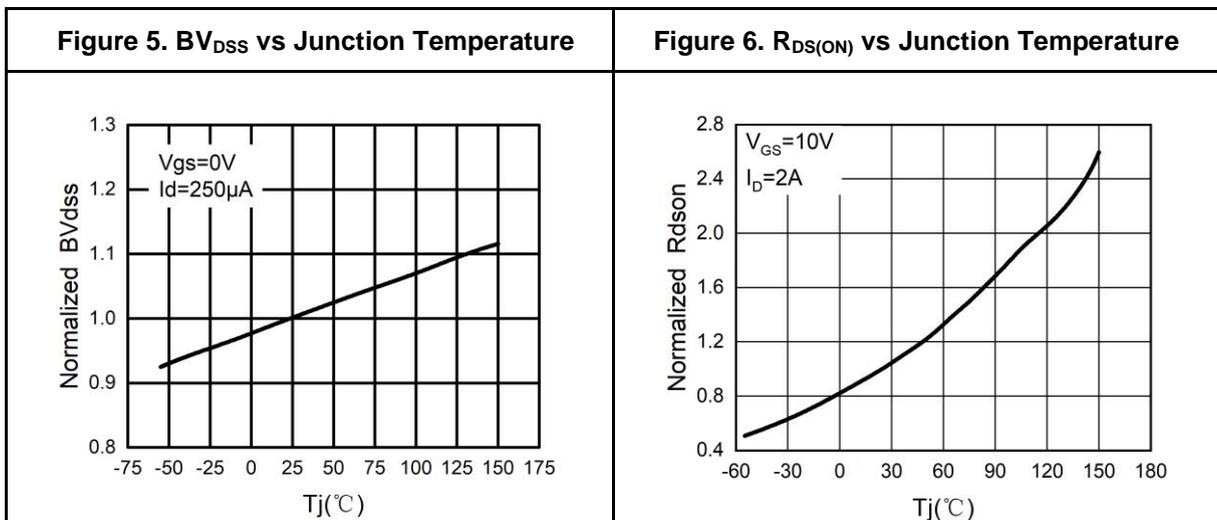
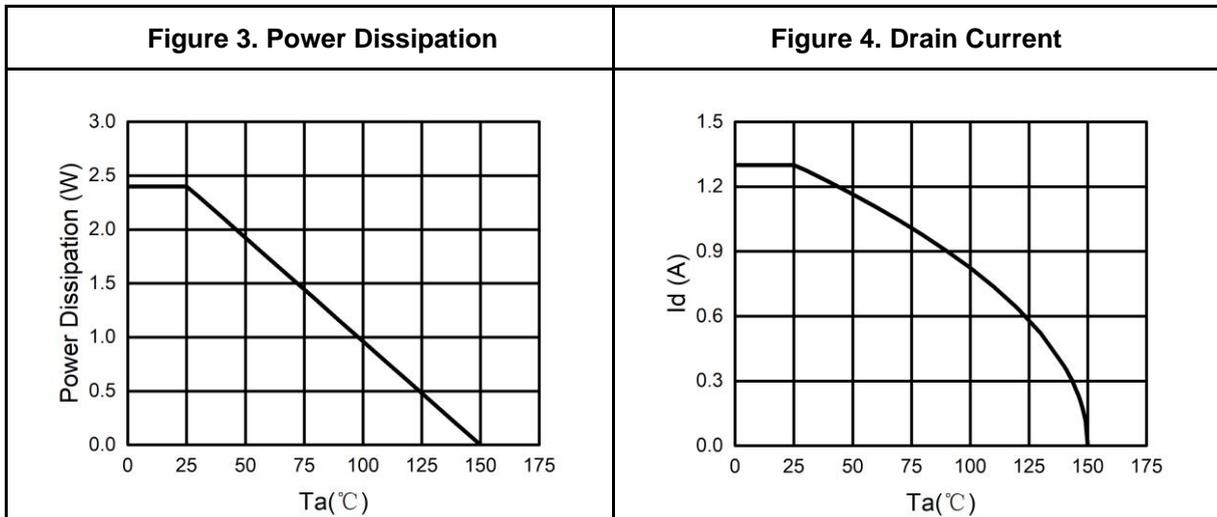
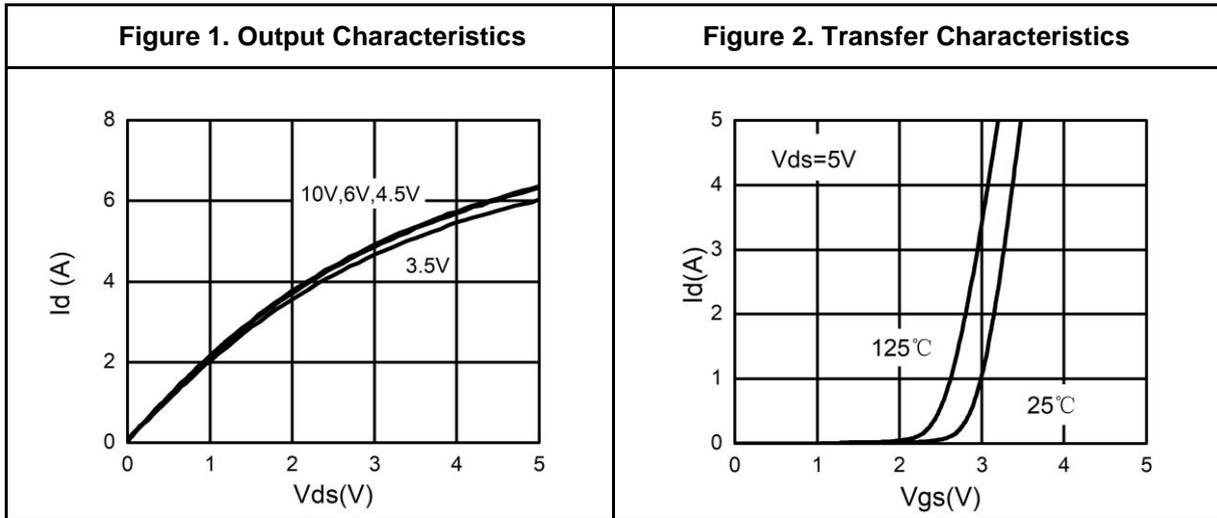
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	200			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=200V, V_{GS}=0V$			1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1		3	V
$g_{FS}$	Forward Transconductance	$V_{DS}=5V, I_D=2A$		8		S
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=1A$		505	606	m $\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1.0MHz$		742		pF
$C_{oss}$	Output Capacitance			14		pF
$C_{rss}$	Reverse Transfer Capacitance			5		pF
<b>Switching Parameters</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DS}=100V, R_L=50\Omega, R_{GEN}=2.5\Omega$		10		nS
$t_r$	Turn-on Rise Time			13		nS
$t_{d(off)}$	Turn-Off Delay Time			16		nS
$t_f$	Turn-Off Fall Time			14		nS
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DS}=100V, I_D=2A$		16.8		nC
$Q_{gs}$	Gate-Source Charge			2.4		nC
$Q_{gd}$	Gate-Drain Charge			6.8		nC
<b>Source-Drain Diode Characteristics</b>						
$I_{SD}$	Source-Drain Current (Body Diode)				1.24	A
$V_{SD}$	Forward on Voltage (Note 2)	$V_{GS}=0V, I_S=1A$			1.2	V

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.  
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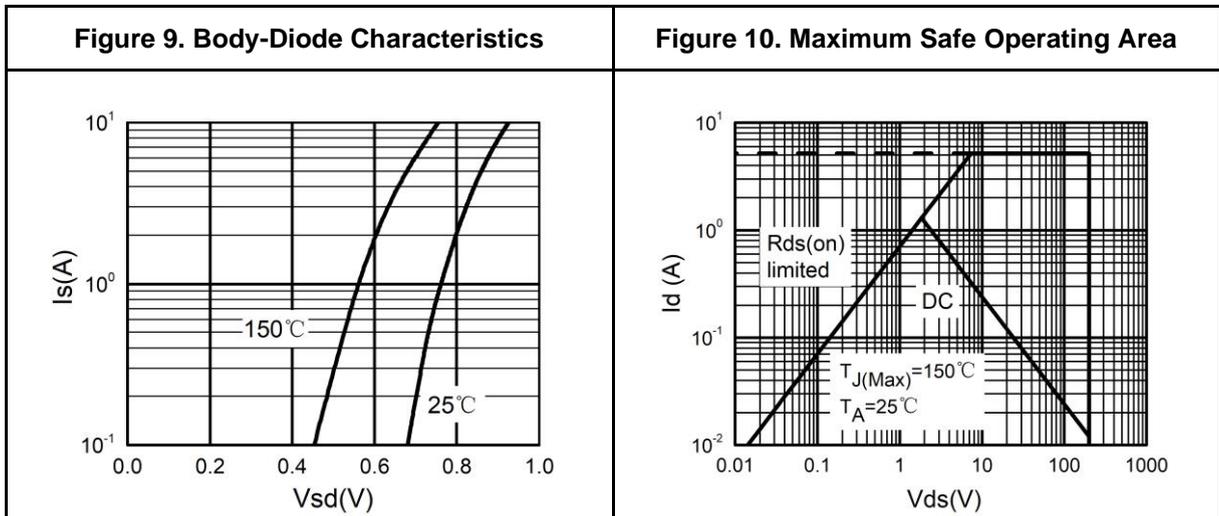
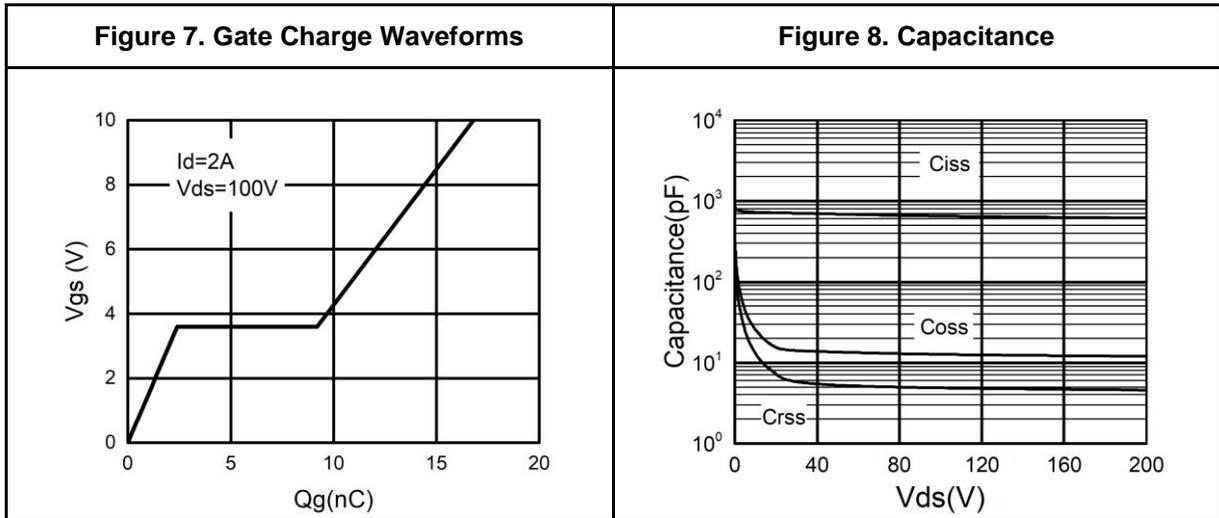
## Typical Electrical And Thermal Characteristics (Curves)





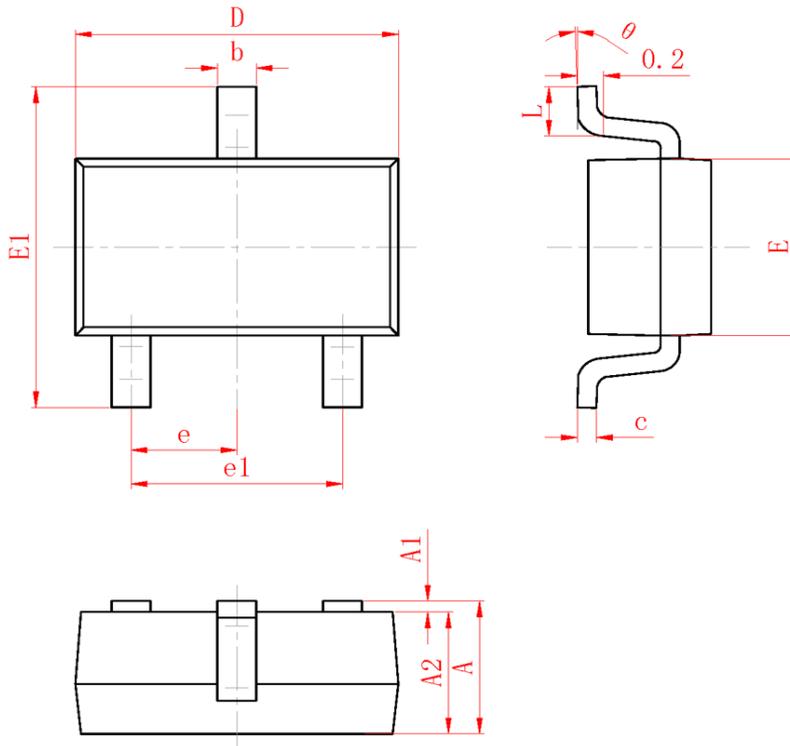
# 200V N-Channel Trench Power MOSFET

## Typical Electrical And Thermal Characteristics (Curves)





SOT-23-3L Package Information



SYMBOL	MILLIMETER	
	MIN	MAX
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.250	0.450
c	0.100	0.200
D	2.820	3.020
E	1.500	1.700
E1	2.650	2.950
e	0.950 (BSC)	
e1	1.800	2.000
L	0.300	0.500
$\theta$	0°	8°

Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.250	0.450
c	0.100	0.200
D	2.820	3.020
E	1.500	1.700
E1	2.650	2.950
e	0.950(BSC)	
e1	1.800	2.000
L	0.300	0.500
$\theta$	0°	8°



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